

Certifications

Approved by ERDF

Section

MV Multifunction

ApplicationField
Laboratory**PRODUCT BENEFITS**

Tuning of the pitch of the tool

TOOL CAPACITY

Diameter 16 - 58 mm
0,630 - 2,283 inch

Non peelable semiconductor screen thickness capacity 0.4 - 1.4 mm / 0.026 - .06 inch

Insulation thickness capacity 7 mm / 0.28 inch

Chamfer angle on the non peelable semiconductor screen 14.5°

TOOL DIMENSIONS

Length 185 mm

Width 90 mm

Height 120 mm

Weight without box 1,4 Kg

Packaging None

Multifunction tool for outer sheath, bonded semiconductor and insulation

TO DO WHAT

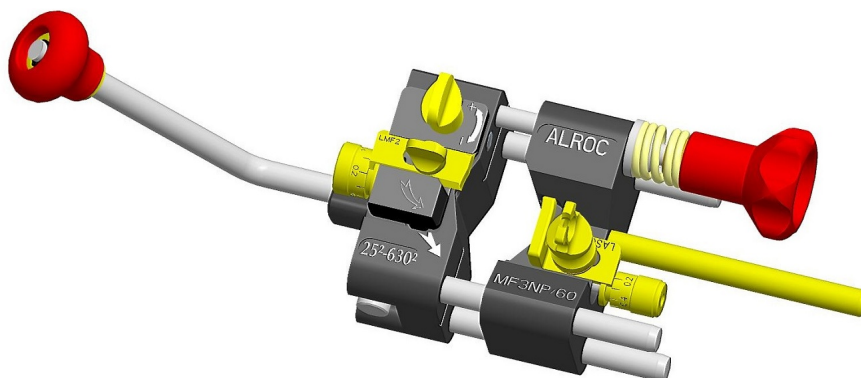
The MF3NP/60 tools enables the user to :

Remove the outer sheath (PE-PVC-PR) with a straight and neat cut.

Remove the bonded semiconductor with a chamfer and a minimum remaining length of semiconductor of 40 mm / 1.57 inch

Remove the insulation with a straight and neat cut

Silicon required for the removal of bonded semiconductor

**Spare part**

LMF2 - Spare blade for primary insulation

PCR - Quick set up right angled 45° handle

196855 - Straight handle M10

108098 - Clamping knob for blade

LASCR1 - Spare blade for bonded semiconductor

PCR - Quick set up right angled 45° handle

Associated tool

GRI-RTE - Scraper for residues of bonded semiconductor screen with protection pouch

LHA - Tool to chamfer insulation



**THORNE &
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MV cables Tools

MF3NP/60



Part Number	Diameter	Tool capacity			Dimensions			Packaging
		Non peelable semiconductor screen thickness capacity	Insulation thickness capacity	Chamfer angle on the non peelable semiconductor screen	Length	Width	Height	
MF3NP/40	16 - 40 mm 0,630 - 1,575 in	0.4 - 1.4 mm / 0.026 - .06 inch	7 mm / 0.28 inch	14.5°	165 mm 6,496 in	80 mm 3,150 in	100 mm 3,937 in	none
MF3NP/60	16 - 58 mm 0,630 - 2,283 in	0.4 - 1.4 mm / 0.026 - .06 inch	7 mm / 0.28 inch	14.5°	185 mm 7,283 in	90 mm 3,543 in	120 mm 4,724 in	none